Embedded system def 1: a computing system designed for a specific purpose - made of purpose-built hardware a software - examples: microwave oven, smart watch, engine central unit, nuclear reactor

- cars contain 70-100 electronic control units (ECUs) and ~100 million lines of code (Bueing 787 has 14 million) soure: Marius Mihailavic, Porsche Engineering Romania

	safety critical	non-safety critical
cost of failure	safety critical high(e.g. loss of life) hard	low
real-time constraints	hard	soft or none
analy sis	worst-case performance	average-case performana testing (partial)
verification	extensive testing/	testing (partial)
	formal methods	0 7
design goals	reliability	quality of service, cost,
/ /	certification	quality of service, cost, time-to-market
design cycle	long (e.g. 10-20 years	short (e.g. les 6 mo
0	for aerospace)	1 yr for smartphones
1	/	

- hardware/software co-design deft: the concurrent design of hardware and software so as to better meet design constraints such as cost, power, and performance

- hw/sw co-design flow artifacts requirements spec. analysis (system spec.) partitioning (hublacks) (architecture) (Sw blecks) design Su designs implementation (Sw midules) integration

1) requirements specification
- functional requirements (what it should do)
e.g. play back mpeg-1 video files
- non-functional requirements (how it should do it)
e.g. max cost, max power draw, min frame rate,
min video file storage, max time to market

2) analysis
- determine how the project can be realized
e.g. algorithms, appertunities for parallelism



3) system specification (aika. high-level spec.)

- implementation independent

- a set of functional blocks

- various models used (statecharts, system C) - possibly

executable or simulatable to facilitate analysis! estimatron e.g. fike selectron, file parsing, image deceding, image unfaut 4) hu/su partitioning
- determine architecture (platform)
- partition functional blocks into hardware blocks
and software blocks 5) architecture - set of processing elements (PEs) that execute
the functional blocks
e.g. FPGA for his blocks (Zyng 7000 Sol programmable logge)
set e.g. ISP for subtware blocks (Zyng 7000 Sol 690Hz dual-core
ARM A9 processor
interconnect between PEs - interconnect between PEs
e.g. Advanced Microcontroller Bus Architecture - includes AXI, APB
for connecting to
lardware - other hw elements such as nemerics, I/O e.g. 512 MiB DDR3 memory, DNA controller, HDMI part



- 6) huse design
 detailed specification for each functional block
 e.g. statemachines and data flow diagrams for hw
 e.g. set of threads and UML diagrams for sw
- 7) implementation
 translate detailed specifications into executable
 modules
 high-level synthesis (ILLS) is a way to automate this
 step
- 8) integration compare modules on the architecture



Design Technologies

1) Networked System

- processing rudes connected by off-chip network

e.g. automotives: Ells connected by CAN bus

(controller area network)

2) Multi-board System
e.g. VME bus chassis with compute, memory and ItO cards
(superceiled by VPX)
- widely used in aerospace and military applications
e.g. PC with PCIe expansion cards
e.g. Arduno expansion boards (shields)

2) Custom PCB
- discrete chips integrated on custom printed circuit bourd
eag. common on commercial applications
e.g. dishvasher controller, rowing machine munitor

4) System-on-Chip (SoC)
- all components on some chip (processors, flash memory, I/O) - DRAM usually separate (different fabrication process)

	(6)
	(network)
edd.	system
Slexi bility	multi-
	material (material)
	PEB)
	380
	integration
	- advantage out integration.
	- in coace of amounication but durith
	- advantages of integration: - increased communication bandwidth - reduced cost, weight, every consumption
	So C circuit technologies D Field Programmable Gode Array (FPGA) - reprogrammable (SRAM) or one-time-programmable (fused) - lower design cost but higher per-unit cost - lower performance (100s of MHz) - good for prototyping and low-volume production
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	- very high design cost but lower per-unit cost
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	- good for high-volume production